



MEP2326W3XL09-H5

Multi-Wavelength SMD Type

Features

- Small 6-Pin package
- Multi-wavelength
Peak wavelength:
SIR=880nm, R=660nm
Dominant wavelength:
G=525nm
- High reliability
- Good spectral matching to Si photo detector
- RoHS compliance

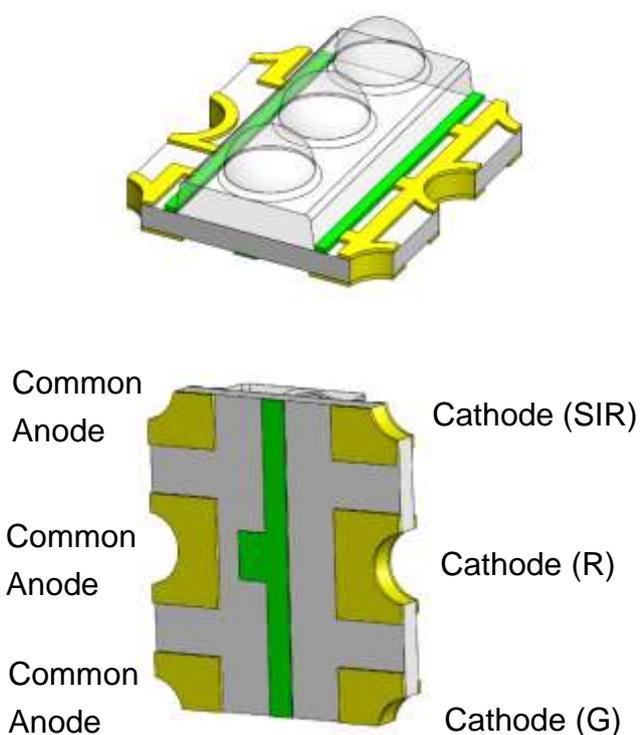
Applications

- Infrared sensor
- Oximeter

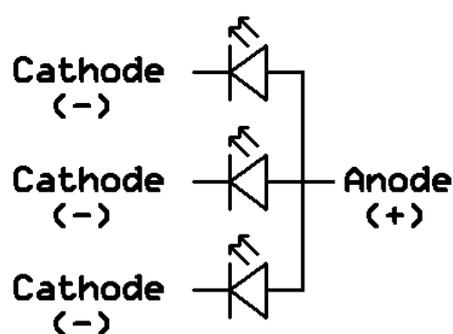
Description

The MEP2326W3XL09-H5 is multiple LED housed in a miniature SMD package. The device has many peak wavelength LED spectrally matched with phototransistor or photodiode.

Package Outline



Schematic





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Absolute Maximum Rating at 25°C

Symbol	Parameters		Ratings	Units	Notes
I _F	Continuous Forward Current	SIR ₍₈₈₀₎	70	mA	
		G ₍₅₂₅₎	20		
		R ₍₆₆₀₎	50		
I _{FP}	Peak Forward Current	SIR ₍₈₈₀₎	0.7	A	1
		G ₍₅₂₅₎	0.1		
		R ₍₆₆₀₎	0.3		
V _R	Reverse Voltage		5	V	
T _{opr}	Operating Temperature		-40 ~ +85	°C	
T _{stg}	Storage Temperature		-40 ~ +100	°C	
T _{sol}	Soldering Temperature		260	°C	2
P _D	Power Dissipation at(or below) 25°C Free Air Temperature	SIR ₍₈₈₀₎	140	mW	
		G ₍₅₂₅₎	68		
		R ₍₆₆₀₎	140		



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Electro-Optical Characteristics $T_A = 25^\circ\text{C}$ (unless otherwise specified)

Optical Characteristics (SIR₍₈₈₀₎)

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
I _e	Radiant Intensity	I _F =20mA	4.0	-	7.4	mW/sr	
		I _F =70mA	-	19	-		
λ _p	Peak Wavelength	I _F =20mA	870	880	890	nm	
Δλ	Spectral Bandwidth	I _F =20mA	-	30	-	nm	
θ _{1/2}	Angle of Half Intensity	I _F =20mA	-	±37.5	-	deg	

Electrical Characteristics (SIR₍₈₈₀₎)

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
V _F	Forward Voltage	I _F =20mA	1.20	1.35	1.7	V	
		I _F =70mA	1.30	1.47	2.0		
I _R	Reverse Current	V _R =5V	-	-	10	μA	

Optical Characteristics (G₍₅₂₅₎)

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
I _v	Luminous Intensity	I _F =20mA	2800	-	5200	mcd	
I _e	Radiant Intensity	I _F =20mA	5.0	7.8	11.0	mW/sr	
P _o	Total Radiated Power	I _F =20mA	-	10	-	mW	
λ _p	Peak Wavelength	I _F =20mA	-	520	-	nm	
λ _d	Dominant Wavelength	I _F =20mA	515	525	535	nm	
Δλ	Spectral Bandwidth	I _F =20mA	-	30	-	nm	
θ _{1/2}	Angle of Half Intensity	I _F =20mA	-	±37.5	-	deg	

Electrical Characteristics (G₍₅₂₅₎)

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
V _F	Forward Voltage	I _F =20mA	1.9	2.75	3.3	V	
I _R	Reverse Current	V _R =5V	-	-	10	μA	



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Optical Characteristics (R₍₆₆₀₎)

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
I _e	Radiant Intensity	I _F =20mA	6	-	14	mW/sr	
		I _F =50mA	-	20	-		
λ _p	Peak Wavelength	I _F =20mA	655	660	665	nm	
Δλ	Spectral Bandwidth	I _F =20mA	-	20	-	nm	
θ _{1/2}	Angle of Half Intensity	I _F =20mA	-	±37.5	-	deg	

Electrical Characteristics (R₍₆₆₀₎)

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
V _F	Forward Voltage	I _F =20mA	1.6	2.0	2.4	V	
		I _F =50mA	1.9	2.3	2.8		
I _R	Reverse Current	V _R =5V	-	-	10	μA	

Notes:

1. I_{FP} Conditions--Pulse Width ≤ 100μs and Duty ≤ 1%.
2. Soldering time ≤ 5 seconds.



Typical Characteristic Curves

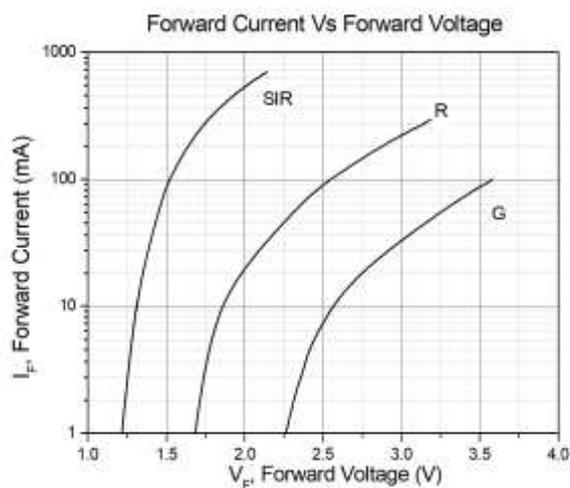


Figure 1

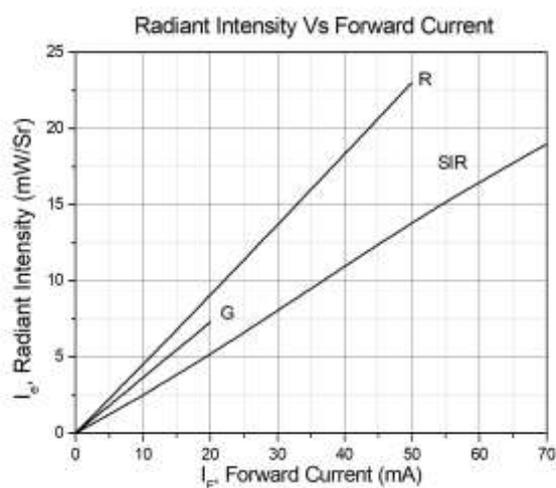


Figure 2

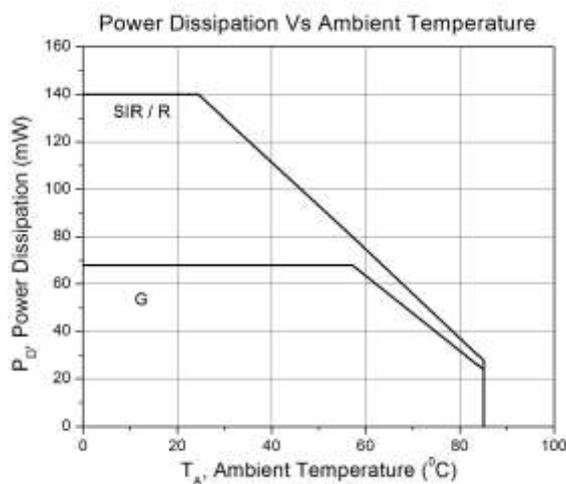


Figure 3

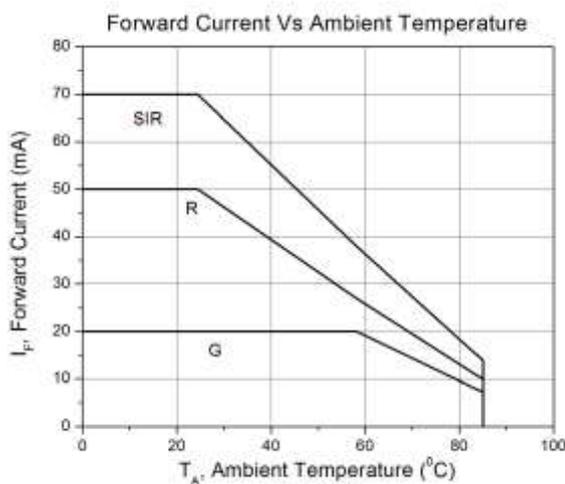


Figure 4

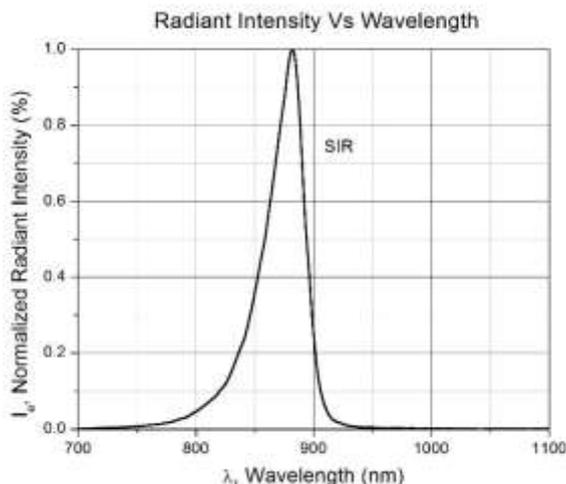


Figure 5

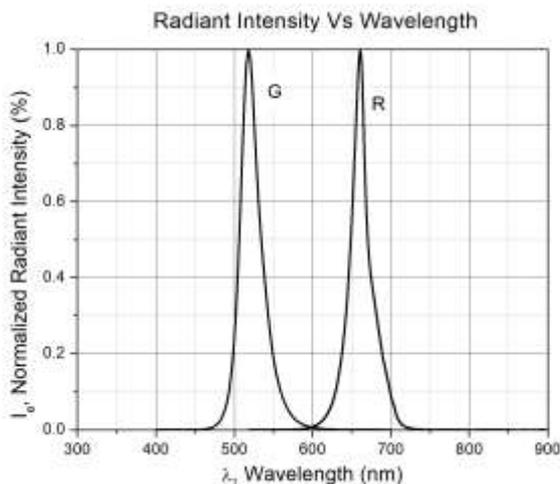
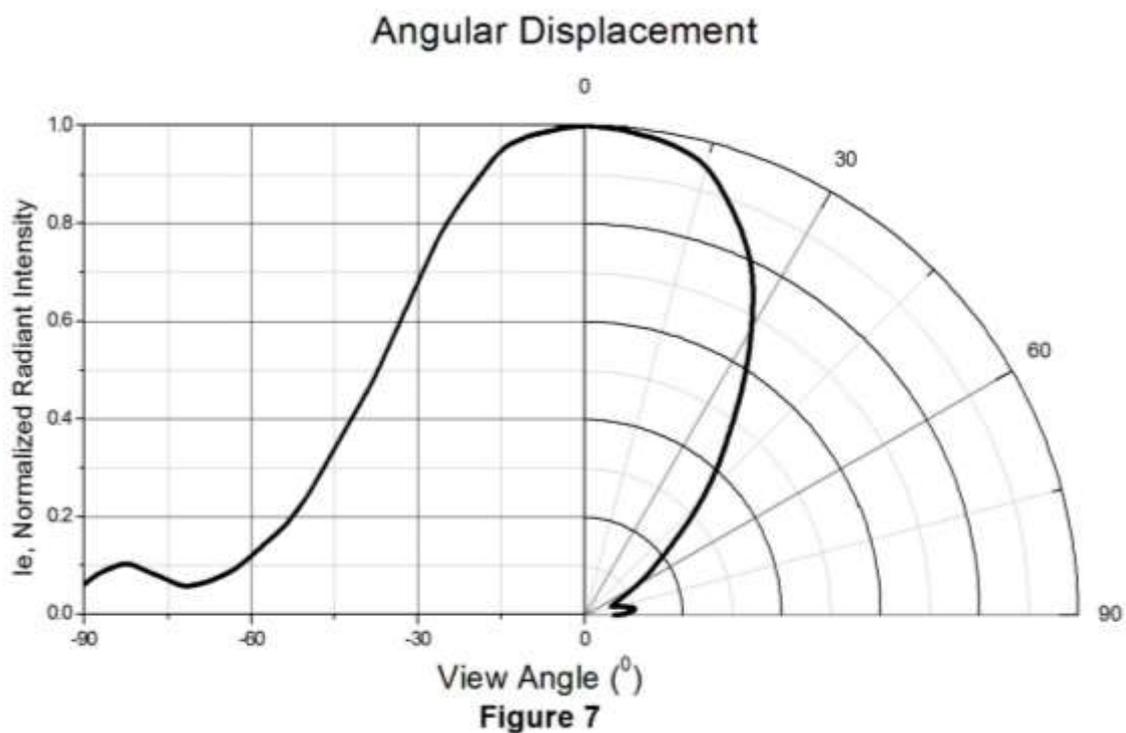


Figure 6



Typical Characteristic Curves

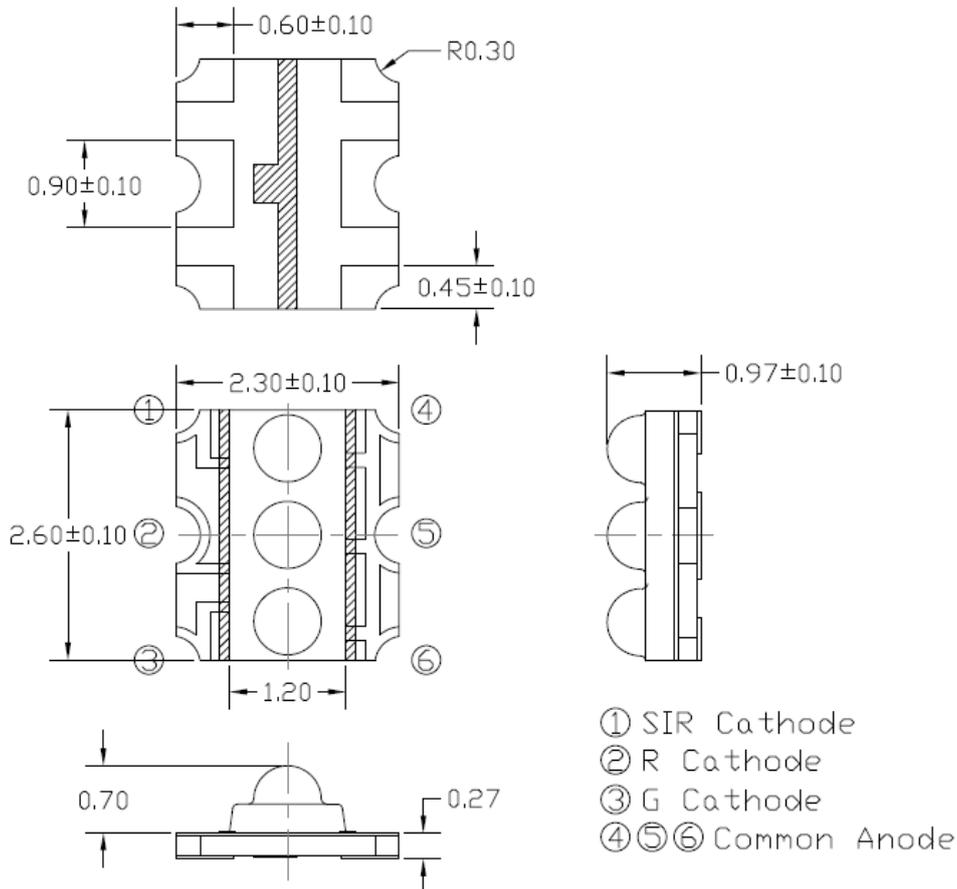




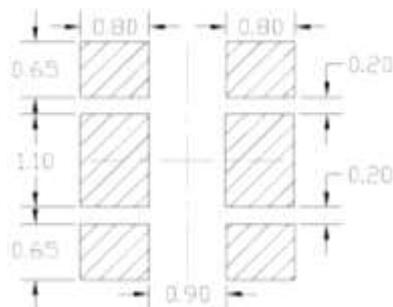
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Multi-Wavelength SMD Type

Package Dimension *All dimensions are in mm, unless otherwise stated*



Recommended Soldering Mask *All dimensions are in mm, unless otherwise stated*



Ordering Information

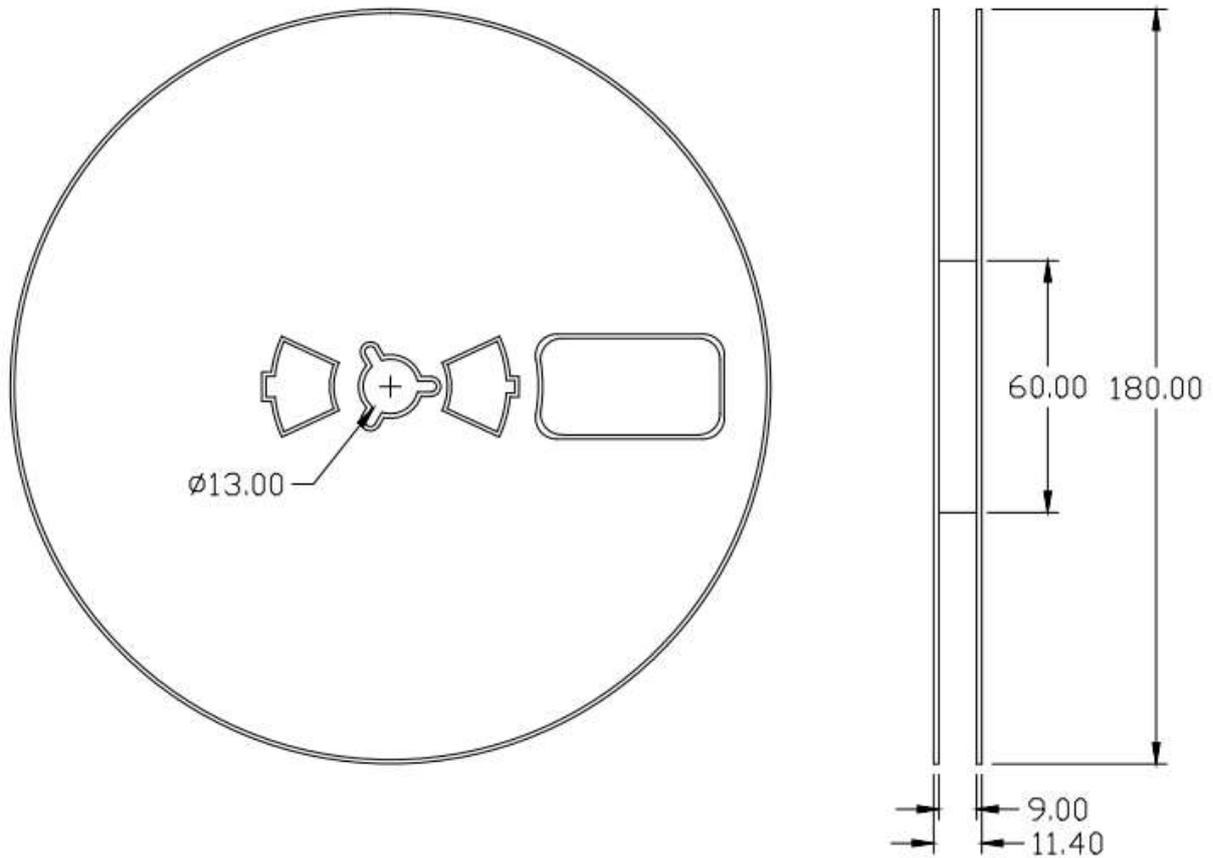
Part Number	Description	Quantity
MEP2326W3XL09-H5	Tape & Reel	4000 pcs



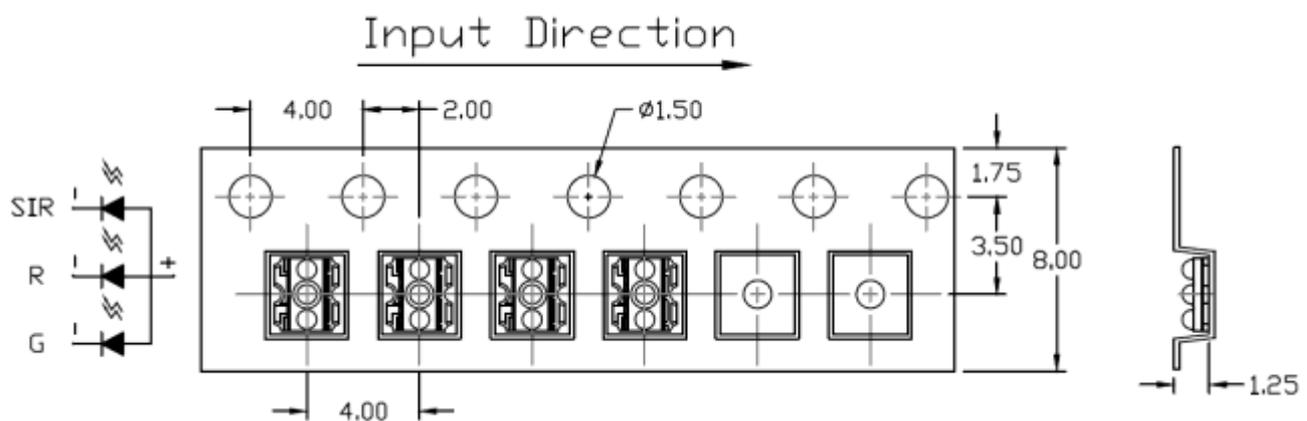
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Reel Dimension *All dimensions are in mm, unless otherwise stated*

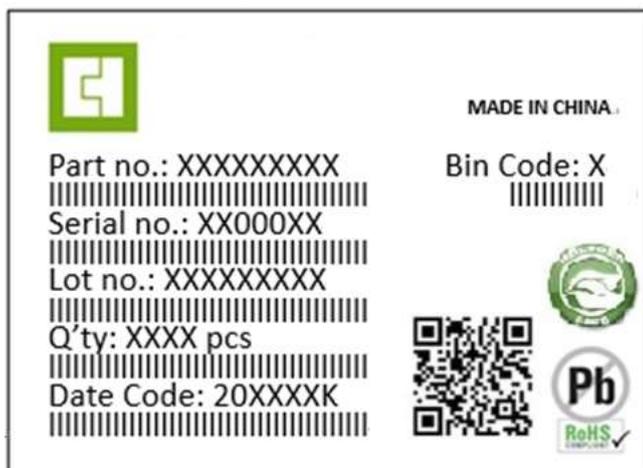


Tape Dimension *All dimensions are in mm, unless otherwise stated*





Label Form Specification



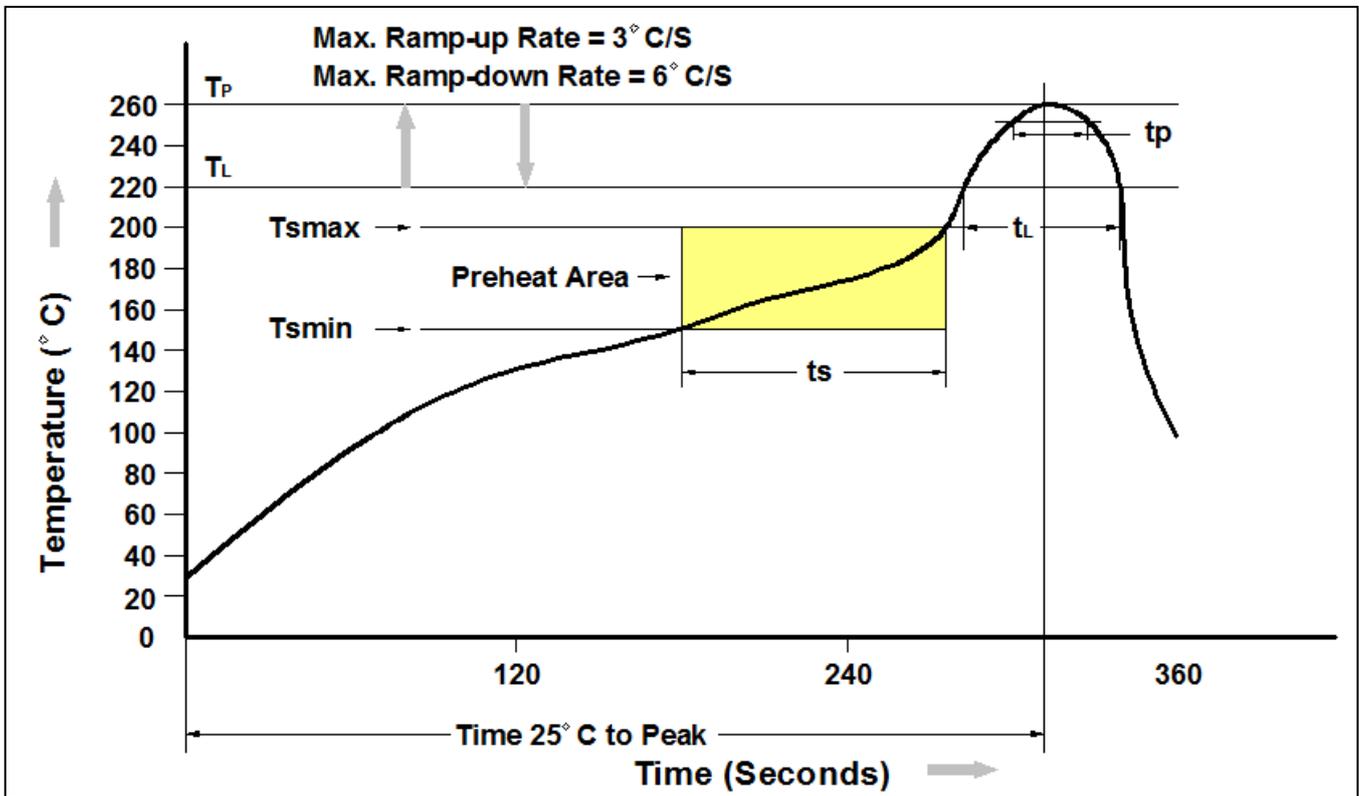
Part no: CTM Production Number
Serial no: Production Number
Lot no: Lot number
Q'ty: Packing Quantity
Date Code: Manufacture Date
Bin Code: 1e Ranks
MADE IN CHINA: Production Place

Storage Condition

1. Do not open moisture proof bag before the products are ready to use.
2. The moisture barrier bag should be stored at 30°C and 90%R.H. max. before opening.
Shelf life of non-opened bag is 12 months after the bag sealing date.
3. After opening the moisture barrier bag floor life is 168h at 30°C/60%RH. max. Unused LEDs should be resealed into moisture barrier bag. (Refer to J-STD-020 Standard)
4. If the moisture absorbent material has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the J-STD-033 Standard conditions.



Reflow Profile



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmmin)	150°C
Temperature Max. (Tsmmax)	200°C
Time (ts) from (Tsmmin to Tsmmax)	60-120 seconds
Ramp-up Rate (tL to tP)	3°C/second max.
Liquidous Temperature (TL)	217°C
Time (tL) Maintained Above (TL)	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (tp) within 5°C of 260°C	30 seconds
Ramp-down Rate (TP to TL)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.



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